

This material is an ABS-like Stereolithography (SLA) resin that has accurate and durable features. Specifically designed for solid-state SLA platforms, it is suitable for various applications, including master patterns, concept models, general components, and functional prototypes.

## MECHANICAL PROPERTIES

Density	1.12 - 1.18 g/cm <sup>3</sup>
Hardness ASTM D 2240	76 - 88 Shore D
Flexural modulus ASTM D 790	2,692 - 2,775 Mpa
Flexural strength ASTM D 790	69 - 74 Mpa
Tensile modulus ASTM D 638	2,589 - 2,695 MPa
Tensile strength ASTM D 638	38 - 56 MPa
Elongation at break ASTM D 638	8 - 12%
Poisson`s Ratio ASTM D 638	0.4 - 0.44
Izod impact strength ASTM D 256	32 - 38 J/m

## THERMAL PROPERTIES

Heat deflection temperature ASTM D 648 @66PSI	39 - 52°C
Glass transition DMA, E" peak	40 - 57 Tg
Coefficient of thermal expansion TMA(T<Tg)	90 - 103°C

## ELECTRICAL PROPERTIES

Dielectric constant ASTM D 150-98	3.3 - 4.2 1 kHz
Dielectric constant ASTM D 150-98	3.2 - 4.0 MHz
Dielectric strength ASTM D 1549-97a	12.8 - 16.1 kV/mm

## APPLICATION

Enclosures  
Controller casings  
Medical device housings

Switch panels  
Trim pieces  
Brackets

\*The above product parameters are typical and not intended as product specifications. Table provided are general and may vary C-UV 9400E CH